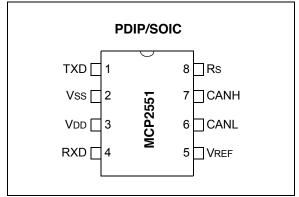


High-Speed CAN Transceiver

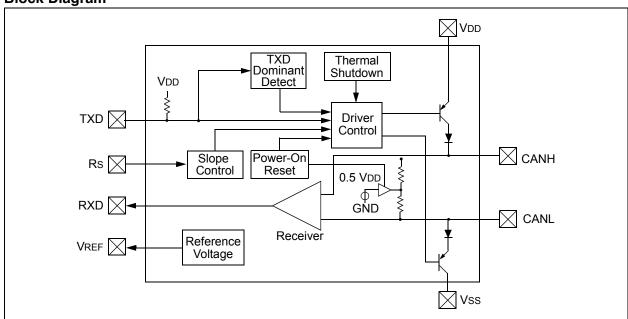
Features

- · Supports 1 Mb/s operation
- Implements ISO-11898 standard physical layer requirements
- · Suitable for 12V and 24V systems
- Externally-controlled slope for reduced RFI emissions
- Detection of ground fault (permanent Dominant) on TXD input
- Power-on Reset and voltage brown-out protection
- An unpowered node or brown-out event will not disturb the CAN bus
- · Low current standby operation
- Protection against damage due to short-circuit conditions (positive or negative battery voltage)
- · Protection against high-voltage transients
- · Automatic thermal shutdown protection
- · Up to 112 nodes can be connected
- High-noise immunity due to differential bus implementation
- · Temperature ranges:
 - Industrial (I): -40°C to +85°C
 - Extended (E): -40°C to +125°C

Package Types



Block Diagram



1.0 DEVICE OVERVIEW

The MCP2551 is a high-speed CAN, fault-tolerant device that serves as the interface between a CAN protocol controller and the physical bus. The MCP2551 device provides differential transmit and receive capability for the CAN protocol controller, and is fully compatible with the ISO-11898 standard, including 24V requirements. It will operate at speeds of up to 1 Mb/s.

Typically, each node in a CAN system must have a device to convert the digital signals generated by a CAN controller to signals suitable for transmission over the bus cabling (differential output). It also provides a buffer between the CAN controller and the high-voltage spikes that can be generated on the CAN bus by outside sources (EMI, ESD, electrical transients, etc.).

1.1 Transmitter Function

The CAN bus has two states: Dominant and Recessive. A Dominant state occurs when the differential voltage between CANH and CANL is greater than a defined voltage (e.g.,1.2V). A Recessive state occurs when the differential voltage is less than a defined voltage (typically 0V). The Dominant and Recessive states correspond to the Low and High state of the TXD input pin, respectively. However, a Dominant state initiated by another CAN node will override a Recessive state on the CAN bus.

1.1.1 MAXIMUM NUMBER OF NODES

The MCP2551 CAN outputs will drive a minimum load of 45Ω , allowing a maximum of 112 nodes to be connected (given a minimum differential input resistance of $20~\text{k}\Omega$ and a nominal termination resistor value of 120Ω).

1.2 Receiver Function

The RXD output pin reflects the differential bus voltage between CANH and CANL. The Low and High states of the RXD output pin correspond to the Dominant and Recessive states of the CAN bus, respectively.

1.3 Internal Protection

CANH and CANL are protected against battery shortcircuits and electrical transients that can occur on the CAN bus. This feature prevents destruction of the transmitter output stage during such a fault condition.

The device is further protected from excessive current loading by thermal shutdown circuitry that disables the output drivers when the junction temperature exceeds a nominal limit of 165°C. All other parts of the chip remain operational, and the chip temperature is lowered due to the decreased power dissipation in the transmitter outputs. This protection is essential to protect against bus line short-circuit-induced damage.

1.4 Operating Modes

The Rs pin allows three modes of operation to be selected:

- · High-Speed
- · Slope-Control
- Standby

These modes are summarized in Table 1-1.

When in High-Speed or Slope-Control mode, the drivers for the CANH and CANL signals are internally regulated to provide controlled symmetry in order to minimize EMI emissions.

Additionally, the slope of the signal transitions on CANH and CANL can be controlled with a resistor connected from pin 8 (Rs) to ground. The slope must be proportional to the current output at Rs, which will further reduce EMI emissions.

1.4.1 HIGH-SPEED

High-Speed mode is selected by connecting the Rs pin to Vss. In this mode, the transmitter output drivers have fast output rise and fall times to support high-speed CAN bus rates.

1.4.2 SLOPE-CONTROL

Slope-Control mode further reduces EMI by limiting the rise and fall times of CANH and CANL. The slope, or slew rate (SR), is controlled by connecting an external resistor (REXT) between Rs and Vol (usually ground). The slope is proportional to the current output at the Rs pin. Since the current is primarily determined by the slope-control resistance value REXT, a certain slew rate is achieved by applying a specific resistance. Figure 1-1 illustrates typical slew rate values as a function of the slope-control resistance value.

1.4.3 STANDBY MODE

The device may be placed in Standby or SLEEP mode by applying a high-level to the Rs pin. In SLEEP mode, the transmitter is switched off and the receiver operates at a lower current. The receive pin on the controller side (RXD) is still functional, but will operate at a slower rate. The attached microcontroller can monitor RXD for CAN bus activity and place the transceiver into normal operation via the Rs pin (at higher bus rates, the first CAN message may be lost).

TABLE 1-1: MODES OF OPERATION

Mode	Current at R _s Pin	Resulting Voltage at Rs Pin
Standby	-IRS < 10 μA	VRS > 0.75 VDD
Slope-Control	10 μA < -IRS < 200 μA	0.4 VDD < VRS < 0.6 VDD
High-Speed	-IRS < 610 μA	0 < VRS < 0.3VDD

TABLE 1-2: TRANSCEIVER TRUTH TABLE

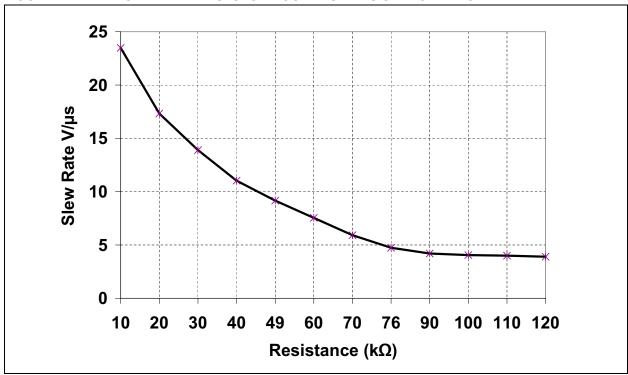
VDD	VRS	TXD	CANH	CANL	Bus State ⁽¹⁾	Rxp ⁽¹⁾
	VRS < 0.75 VDD	0	HIGH	LOW	Dominant	0
$4.5V \leq V_{DD} \leq 5.5V$	VR5 ~ 0.75 VDD	1 or floating	Not Driven	Not Driven	Recessive	1
	VRS > 0.75 VDD	Х	Not Driven	Not Driven	Recessive	1
\/pop 4\/pp 445\/	VRS < 0.75 VDD	0	HIGH	LOW	Dominant	0
VPOR < VDD < 4.5V (See Note 3)	VRS < 0.75 VDD	1 or floating	Not Driven	Not Driven	Recessive	1
(See Note 3)	VRS > 0.75 VDD	Х	Not Driven	Not Driven	Recessive	1
0 < VDD < VPOR	Х	Х	X Not Driven/ No Load		High Impedance	Х

Note 1: If another bus node is transmitting a Dominant bit on the CAN bus, then RXD is a logic '0'.

2: X = "don't care".

3: Device drivers will function, although outputs are not ensured to meet the ISO-11898 specification.

FIGURE 1-1: SLEW RATE VS. SLOPE-CONTROL RESISTANCE VALUE



1.5 TXD Permanent Dominant Detection

If the MCP2551 detects an extended Low state on the TXD input, it will disable the CANH and CANL output drivers in order to prevent the corruption of data on the CAN bus. The drivers are disabled if TXD is Low for more than 1.25 ms (minimum). This implies a maximum bit time of 62.5 μs (16 kb/s bus rate), allowing up to 20 consecutive transmitted Dominant bits during a multiple bit error and error frame scenario. The drivers remain disabled as long as TXD remains Low. A rising edge on TXD will reset the timer logic and enable the CANH and CANL output drivers.

1.6 Power-on Reset

When the device is powered on, CANH and CANL remain in a high-impedance state until VDD reaches the voltage-level VPORH. In addition, CANH and CANL will remain in a high-impedance state if TXD is Low when VDD reaches VPORH. CANH and CANL will become active only after TXD is asserted High. Once powered on, CANH and CANL will enter a high-impedance state if the voltage level at VDD falls below VPORL, providing voltage brown-out protection during normal operation.

1.7 Pin Descriptions

The 8-pin pinout is listed in Table 1-3.

TABLE 1-3: MCP2551 PINOUT

Pin Number	Pin Name	Pin Function	
1	TXD	Transmit Data Input	
2	Vss	Ground	
3	VDD	Supply Voltage	
4	RXD	Receive Data Output	
5	VREF	Reference Output Voltage	
6	CANL	CAN Low-Level Voltage I/O	
7	CANH	CAN High-Level Voltage I/O	
8	Rs	Slope-Control Input	

1.7.1 TRANSMITTER DATA INPUT (TXD)

TXD is a TTL-compatible input pin. The data on this pin is driven out on the CANH and CANL differential output pins. It is usually connected to the transmitter data output of the CAN controller device. When TXD is Low, CANH and CANL are in the Dominant state. When TXD is High, CANH and CANL are in the Recessive state, provided that another CAN node is not driving the CAN bus with a Dominant state. TXD has an internal pull-up resistor (nominal 25 $k\Omega$ to VDD).

1.7.2 GROUND SUPPLY (Vss)

Ground supply pin.

1.7.3 SUPPLY VOLTAGE (V_{DD})

Positive supply voltage pin.

1.7.4 RECEIVER DATA OUTPUT (RXD)

RXD is a CMOS-compatible output that drives High or Low depending on the differential signals on the CANH and CANL pins and is usually connected to the receiver data input of the CAN controller device. RXD is High when the CAN bus is Recessive and Low in the Dominant state.

1.7.5 REFERENCE VOLTAGE (VREF)

Reference Voltage Output (defined as VDD/2).

1.7.6 CAN LOW (CANL)

The CANL output drives the Low side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.7 CAN HIGH (CANH)

The CANH output drives the high-side of the CAN differential bus. This pin is also tied internally to the receive input comparator.

1.7.8 SLOPE RESISTOR INPUT (Rs)

The Rs pin is used to select High-Speed, Slope-Control or Standby modes via an external biasing resistor.

2.0 ELECTRICAL CHARACTERISTICS

2.1 Terms and Definitions

A number of terms are defined in ISO-11898 that are used to describe the electrical characteristics of a CAN transceiver device. These terms and definitions are summarized in this section.

2.1.1 BUS VOLTAGE

VCANL and VCANH denote the voltages of the bus line wires CANL and CANH relative to ground of each individual CAN node.

2.1.2 COMMON MODE BUS VOLTAGE RANGE

Boundary voltage levels of VCANL and VCANH with respect to ground, for which proper operation will occur, if up to the maximum number of CAN nodes are connected to the bus.

2.1.3 DIFFERENTIAL INTERNAL CAPACITANCE, CDIFF (OF A CAN NODE)

Capacitance seen between CANL and CANH during the Recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.4 DIFFERENTIAL INTERNAL RESISTANCE, RDIFF (OF A CAN NODE)

Resistance seen between CANL and CANH during the Recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.5 DIFFERENTIAL VOLTAGE, VDIFF (OF CAN BUS)

Differential voltage of the two-wire CAN bus, value VDIFF = VCANH - VCANL.

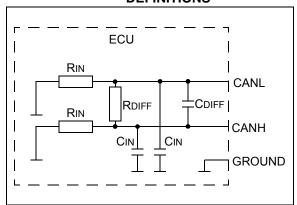
2.1.6 INTERNAL CAPACITANCE, CIN (OF A CAN NODE)

Capacitance seen between CANL (or CANH) and ground during the Recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

2.1.7 INTERNAL RESISTANCE, RIN (OF A CAN NODE)

Resistance seen between CANL (or CANH) and ground during the Recessive state when the CAN node is disconnected from the bus (see Figure 2-1).

FIGURE 2-1: PHYSICAL LAYER DEFINITIONS



Absolute Maximum Ratings†

VDD	7.0V
DC Voltage at TXD, RXD, VREF and Vs	0.3V to VDD + 0.3V
DC Voltage at CANH, CANL (Note 1)	42V to +42V
Transient Voltage on Pins 6 and 7 (Note 2)	250V to +250V
Storage temperature	55°C to +150°C
Operating ambient temperature	40°C to +125°C
Virtual Junction Temperature, TvJ (Note 3)	40°C to +150°C
Soldering temperature of leads (10 seconds)	+300°C
ESD protection on CANH and CANL pins (Note 4)	6 kV
ESD protection on all other pins (Note 4)	4 kV
Note 1: Short-circuit applied when TXD is High and Low.	

- - 2: In accordance with ISO-7637.
 - 3: In accordance with IEC 60747-1.
 - 4: Classification A: Human Body Model.

† NOTICE: Stresses above those listed under "Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2.2 DC Characteristics

DC Specifications			Electrical Characteristics: Industrial (I): TAMB = -40°C to +85°C VDD = 4.5V to 5.5V Extended (E): TAMB = -40°C to +125°C VDD = 4.5V to 5.5V				
Param No.	Sym Characteristic		Min	Max	Units	Conditions	
Supply							
D1			_	75	mA	Dominant; VTXD = 0.8V; VDD	
D2			_	10	mA	Recessive; VTXD = +2V; Rs = 47 kW	
D3	IDD	Supply Current	_	365	μA	-40°C ≤ T _{AMB} ≤ +85°C, Standby; (Note 2)	
DS			_	465	μA	$-40^{\circ}\text{C} \le \text{T}_{AMB} \le +125^{\circ}\text{C},$ Standby; (Note 2)	
D4	VPORH	High-level of the Power-on Reset comparator	3.8	4.3	٧	CANH, CANL outputs are active when VDD > VPORH	
D5	VPORL	Low-level of the Power-on Reset comparator	3.4	4.0	V	CANH, CANL outputs are not active when VDD < VPORL	
D6	VPORD	Hysteresis of Power-on Reset comparator	0.3	0.8	>	Note 1	
Bus Lin	e (CANH; CANL)	Transmitter					
D7	VCANH _{(r);} VCANL _(r)	CANH, CANL Recessive bus voltage	2.0	3.0	V	VTXD = VDD; no load.	
D8	IO(CANH)(reces)	December output output	-2	+2	mA	-2V < V(CAHL,CANH) < +7V, 0V <vdd 5.5v<="" <="" td=""></vdd>	
D9	IO(CANL)(reces)	Recessive output current	-10	+10	mA	-5V < V(CANL,CANH) < +40V, 0V < VDD < 5.5V	
D10	Vo(canh)	CANH Dominant output voltage	2.75	4.5	٧	VTXD = 0.8V	
D11	Vo(canl)	CANL Dominant output voltage	0.5	2.25	٧	VTXD = 0.8V	
D12	VDIFF(r)(o)	Recessive differential output voltage	-500	+50	mV	VTXD = 2V; no load	
D13	VDIFF(d)(o)	Dominant differential output voltage	1.5	3.0	٧	VTXD = 0.8V; VDD = 5V 40W < RL < 60W (Note 2)	
D14		CANH short-circuit	_	-200	mA	VCANH = -5V	
D15	Io(SC)(CANH)	output current	_	-100 (typical)	mA	VCANH = -40V, +40V. (Note 1)	
D16	Io(SC)(CANL)I	CANL short-circuit output current	_	200	mA	VCANL = -40V, +40V. (Note 1)	
D17	VDIET/r\/i\	Recessive differential	-1.0	+0.5	٧	-2V < V(CANL, CANH) < +7V (Note 3)	
ווט	VDIFF(r)(i)	input voltage	-1.0	+0.4	٧	-12V < V(CANL, CANH) < +12V (Note 3)	

Note 1: This parameter is periodically sampled and not 100% tested.

^{2:} ITXD = IRXD = IVREF = 0 mA; 0V < VCANL < VDD; 0V < VCANH < VDD; VRS = VDD

^{3:} This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

2.2 DC Characteristics (Continued)

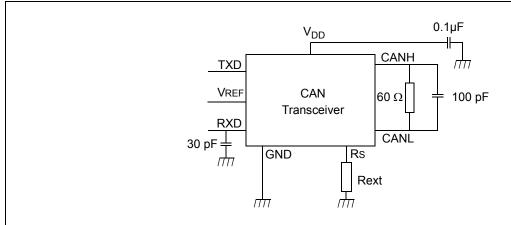
DC Specifications (Continued)		Industri	Electrical Characteristics: Industrial (I): TAMB = -40°C to +85°C VDD = 4.5V to 5.5 Extended (E): TAMB = -40°C to +125°C VDD = 4.5V to 5.5				
Param No.	Sym Characteristic		Min	Max	Units	Conditions	
Bus Line	e (CANH; CANL) Receiver: [TXD = 2V; pins 6	and 7	externally	driven]		
D18	VDIFF(d)(i)	Dominant differential	0.9	5.0	V	-2V < V(CANL, CANH) < +7V (Note 3)	
Dio	VDIFF(U)(I)	input voltage	1.0	5.0	V	-12V < V(CANL, CANH) < +12V (Note 3)	
D19	VDIFF(h)(i)	Differential input hysteresis	100	200	mV	See Figure 2-3 (Note 1)	
D20	RIN	CANH, CANL Common- mode input resistance	5	50	kW		
D21	Rın(d)	Deviation between CANH and CANL Common-mode input resistance	-3	+3	%	VCANH = VCANL	
Bus Line	(CANH; CANL) Receiver: [TXD = 2V; pins 6	and 7	externally	driven]		
D22	Rdiff	Differential input resistance	20	100	kW		
D24	lLi	CANH, CANL input leakage current	_	150	μA	VDD < VPOR; VCANH = VCANL = +5V	
Transmi	tter Data Input ((TXD)					
D25	VIH	High-level input voltage	2.0	Vdd	V	Output Recessive	
D26	VIL	Low-level input voltage	Vss	+0.8	V	Output Dominant	
D27	IIН	High-level input current	-1	+1	μΑ	VTXD = VDD	
D28	lıL	Low-level input current	-100	-400	μΑ	VTXD = 0V	
Receive	r Data Output (F	RXD)					
D31	Vон	High-level output voltage	0.7 VD D	_	٧	Iон = 8 mA	
D32	Vol	Low-level output voltage		0.8	V	IOL = 8 mA	
Voltage	Reference Outp	out (VREF)					
D33	VREF	Reference output voltage	0.45 V DD	0.55 VD D	>	-50 μA < IVREF < 50 μA	
Standby	/Slope-Control	(Rs pin)					
D34	Vsтв	Input voltage for standby mode	0.75 V DD		V		
D35	ISLOPE	Slope-control mode current	-10	-200	μA		
D36	VSLOPE	Slope-control mode voltage	0.4 VD D	0.6 VDD	٧		
Thermal	Shutdown						
D37	TJ _(sd)	Shutdown junction temperature	155	180	°C	Note 1	
D38	TJ _(h)	Shutdown temperature hysteresis	20	30	°C	-12V < V(CANL, CANH) < +12V (Note 3)	

Note 1: This parameter is periodically sampled and not 100% tested.

^{2:} ITXD = IRXD = IVREF = 0 mA; 0V < VCANL < VDD; 0V < VCANH < VDD; VRS = VDD

^{3:} This is valid for the receiver in all modes; High-speed, Slope-control and Standby.

FIGURE 2-1: TEST CIRCUIT FOR ELECTRICAL CHARACTERISTICS



Note: Rs may be connected to VDD or GND via a load resistor depending on desired operating mode as described in **Section 1.7.3** "**Supply Voltage (V_{DD})**".

FIGURE 2-2: TEST CIRCUIT FOR AUTOMOTIVE TRANSIENTS

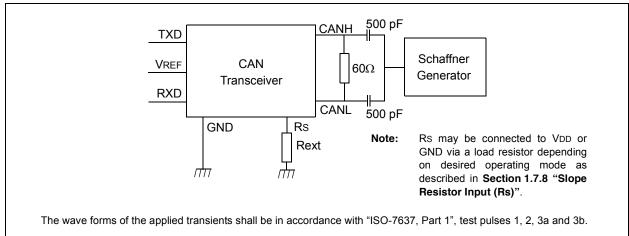
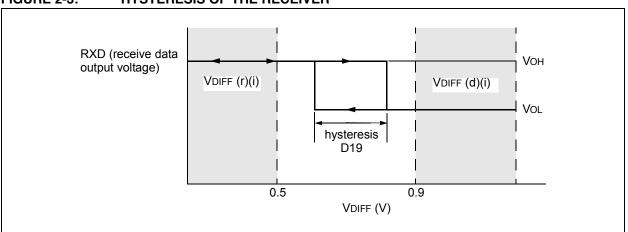


FIGURE 2-3: HYSTERESIS OF THE RECEIVER



2.3 AC Characteristics

AC Specifications			Industrial (-40°C to) +85°C VDD = 4.5V to 5.5V) +125°C VDD = 4.5V to 5.5V
Param No.	Sym	Characteristic	Min	Max	Units	Conditions
1	tвіт	Bit time	1	62.5	μs	VRS = 0V
2	fвіт	Bit frequency	16	1000	kHz	VRS = 0V
3	TtxL2bus(d)	Delay TXD to bus active	_	70	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ VRS = 0V
4	TtxH2bus(r)	Delay TXD to bus inactive	_	125	ns	$\label{eq:controller} \begin{array}{l} -40^{\circ}C \leq TAMB \leq +85^{\circ}C, \\ VRS = 0V \end{array}$
7	112003(1)	Delay TAD to bus mactive	_	170	ns	$\label{eq:continuous} \begin{array}{l} -40^{\circ}C \leq TAMB \leq +125^{\circ}C, \\ VRS = 0V \end{array}$
5	Ttyl 2py(d)	Dolov TVD to receive active	_	130	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ VRS = 0V
5	TtxL2rx(d)	Delay TXD to receive active	_	250	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ Rs = 47 k Ω
			_	175	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +85^{\circ}\text{C},$ VRS = 0V
	Th.: 110 : / -:)	Delay TXD to receiver	_	225	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +85^{\circ}\text{C},$ Rs = 47 k Ω
6	TtxH2rx(r)	inactive	_	235	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ VRS = 0V
			_	400	ns	$-40^{\circ}\text{C} \le \text{TAMB} \le +125^{\circ}\text{C},$ Rs = 47 k Ω
7	SR	CANH, CANL slew rate	5.5	8.5	V/µs	Refer to Figure 2-1; Rs = 47 k Ω , (Note 1)
10	twake	Wake-up time from standby (Rs pin)	_	5	μs	See Figure 2-5
11	TbusD2rx(s)	Bus Dominant to RXD Low (Standby mode)	_	550	ns	VRS = +4V; (See Figure 2-6)
12	CIN(CANH) CIN(CANL)	CANH; CANL input capacitance	_	20 (typical)	pF	1 Mb/s data rate; VTXD = VDD, (Note 1)
13	CDIFF	Differential input capacitance	_	10 (typical)	pF	1 Mb/s data rate (Note 1)
14	TtxL2busZ	TX Permanent Dominant Timer Disable Time	1.25	4	ms	
15	TtxR2pdt(res)	TX Permanent Dominant Timer Reset Time	_	1	μs	Rising edge on TXD while device is in permanent Dominant state

Note 1: This parameter is periodically sampled and not 100% tested.

2.4 Timing Diagrams and Specifications

FIGURE 2-4: TIMING DIAGRAM FOR AC CHARACTERISTICS

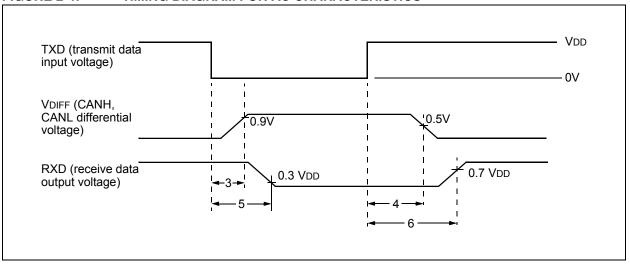


FIGURE 2-5: TIMING DIAGRAM FOR WAKE-UP FROM STANDBY

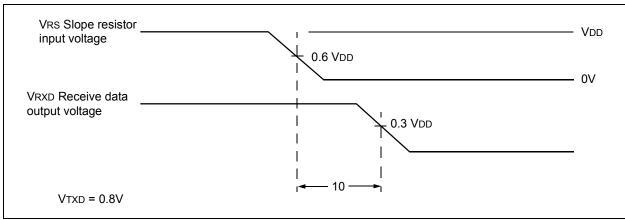
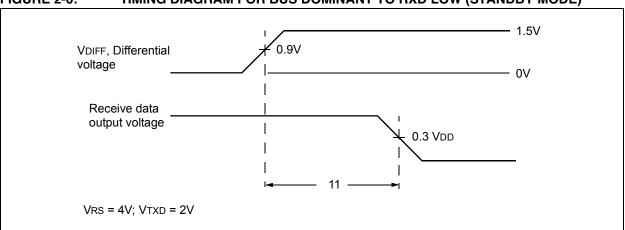


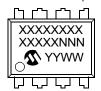
FIGURE 2-6: TIMING DIAGRAM FOR BUS DOMINANT TO RXD LOW (STANDBY MODE)

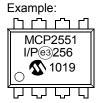


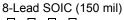
3.0 PACKAGING INFORMATION

3.1 **Package Marking Information**

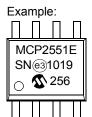
8-Lead PDIP (300 mil)











Legend: XX...X Customer-specific information

Υ Year code (last digit of calendar year) Year code (last 2 digits of calendar year) YY WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

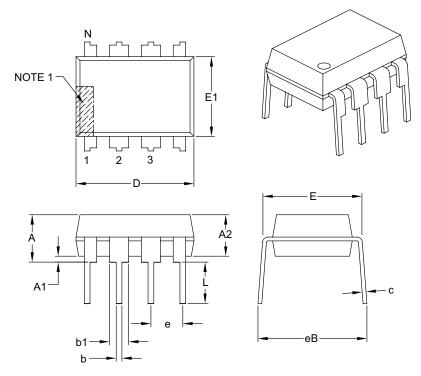
e3 Pb-free JEDEC designator for Matte Tin (Sn)

This package is Pb-free. The Pb-free JEDEC designator (@3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Solution For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES		
	Dimension Limits	MIN	NOM	MAX	
Number of Pins	N		8	•	
Pitch	е		.100 BSC		
Top to Seating Plane	A	_	_	.210	
Molded Package Thickness	A2	.115	.130	.195	
Base to Seating Plane	A1	.015	_	-	
Shoulder to Shoulder Width	E	.290	.310	.325	
Molded Package Width	E1	.240	.250	.280	
Overall Length	D	.348	.365	.400	
Tip to Seating Plane	L	.115	.130	.150	
Lead Thickness	С	.008	.010	.015	
Upper Lead Width	b1	.040	.060	.070	
Lower Lead Width	b	.014	.018	.022	
Overall Row Spacing §	eB	_	_	.430	

Notes:

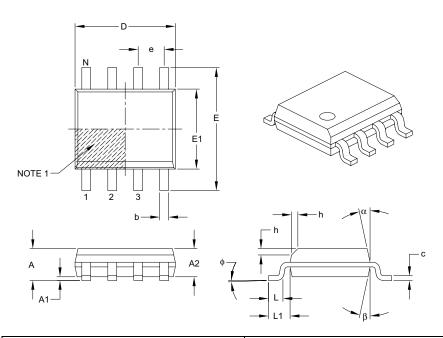
- 1. Pin 1 visual index feature may vary, but must be located with the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018E

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX	
Number of Pins	N		8		
Pitch	е		1.27 BSC		
Overall Height	Α	_	_	1.75	
Molded Package Thickness	A2	1.25	_	_	
Standoff §	A1	0.10	_	0.25	
Overall Width E		6.00 BSC			
Molded Package Width	E1	1 3.90 BSC			
Overall Length	D		4.90 BSC		
Chamfer (optional)	h	0.25	_	0.50	
Foot Length	L	0.40	_	1.27	
Footprint	L1		1.04 REF		
Foot Angle	ф	0°	_	8°	
Lead Thickness	С	0.17	_	0.25	
Lead Width	b	0.31	_	0.51	
Mold Draft Angle Top	α	5°	_	15°	
Mold Draft Angle Bottom	β	5°	_	15°	

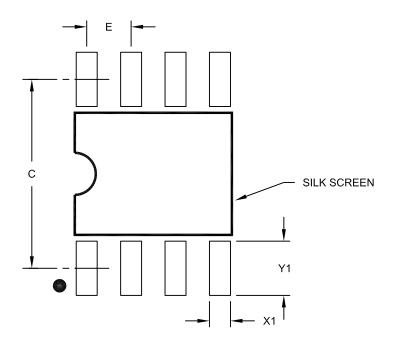
Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-057B

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	N	ILLIMETER	S	
Dimension Limits		MIN	NOM	MAX
Contact Pitch	Е		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

APPENDIX A: REVISION HISTORY

Revision F (July 2010)

The following is the list of modifications:

1. Updates to the packaging diagrams.

Revision E (January 2007)

The following is the list of modifications:

1. Updates to the packaging diagrams.

Revision D (October 2003)

The following is the list of modifications:

1. Undocumented changes.

Revision C (November 2002)

The following is the list of modifications:

1. Undocumented changes.

Revision B (June 2002)

The following is the list of modifications:

1. Undocumented changes.

Revision A (June 2001)

· Original Release of this Document.

PRODUCT IDENTIFICATION SYSTEM

 $\underline{\text{To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales of fice.}\\$

Examples:
a) MCP2551-I/P: Industrial temperature, PDIP package.
b) MCP2551-E/P: Extended temperature, PDIP package.
c) MCP2551-I/SN: Industrial temperature, SOIC package.
d) MCP2551T-I/SN: Tape and Reel, Industrial Temperature,
SOIC package.
e) MCP2551T-E/SN: Tape and Reel, Extended Temperature,
SOIC package. f) MCP2551-E/SN: Extended Temperature, SOIC package.

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the
 intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- · Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, Keeloq, Keeloq logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Octopus, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN:

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV ISO/TS 16949:2002



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199
Tel: 480-792-7200

Fax: 480-792-7277 Technical Support:

http://support.microchip.com

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca. IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario, Canada

Tel: 905-673-0699

Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon

Hong Kong Tel: 852-2401-1200

Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung Tel: 886-7-536-4818

Fax: 886-7-536-4803

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91 **UK - Wokingham**

Tel: 44-118-921-5869 Fax: 44-118-921-5820

01/05/10